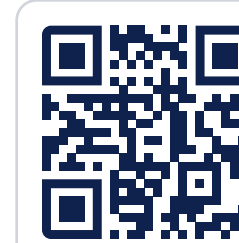


● Research for ALD

Beneq TFS 500



OVERVIEW



The Beneq TFS 500 extends the versatility of the TFS series for bigger substrate and batch sizes for the most demanding R&D projects. The TFS 500 is the perfect tool for scaling R&D efforts and ramping into an ALD pilot production phase.

FEATURES

Scalable

The TFS 500 maintains all the flexible perks of the TFS 200 but on a bigger scale. A larger chamber enables deposition on new substrates, like 300 mm wafers, and the processing of more sizable batches of 3D objects.

Ergonomic

A front-mounted loading door and external precursor lines make depositions in the TFS 500 easily adjustable, accessible and with quick turnaround times.

Integratable

The TFS 500 can be seamlessly integrated with a large glove box and manual load lock for additional wafer processing. Plasma-enhanced ALD is available, as well as custom reaction chamber designs for specific substrate or application needs.

Application examples

- Al_2O_3 ALD on barrier applications
- HfO_2 , SiO_2 and SiN ALD on semiconductor applications
- SnO_2 ALD for photovoltaic cells
- TiN and NbN ALD for superconductor applications

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Beneq TFS 500



SPECIFICATIONS

Process type	Thermal ALD, Plasma-enhanced ALD
Usage	Research & Development, Production
Integration	Stand-alone, Cluster, Glovebox, Loadlock
Dimensions (L x W x H)	1800 x 900 x 2033 mm
Temperature range	25–500 °C
Substrate type	• Round wafers, up to 300 mm • Square wafers, up to 300 x 300 mm • Wafer batch / 3D parts, up to 300 x 350 x 125 mm • Porous and high aspect ratio structures

RESEARCH EQUIPMENT

Beneq maintains the largest install base of ALD research equipment for academic research and corporate R&D. We are dedicated to providing customers with premium, versatile research equipment to meet demanding lab environments and enable cutting-edge results.



Beneq TFS 200

The most recognized ALD platform used by academic researchers and corporate R&D teams worldwide.